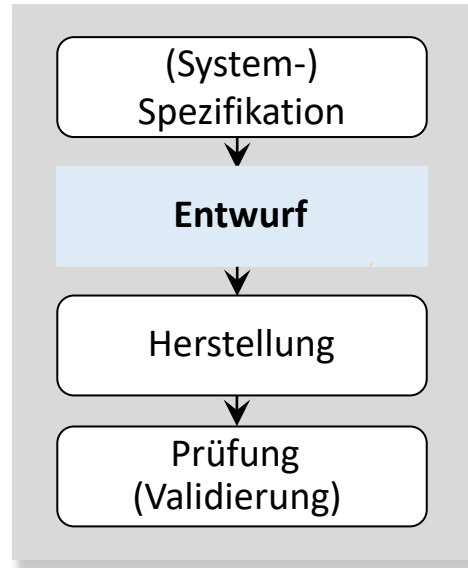
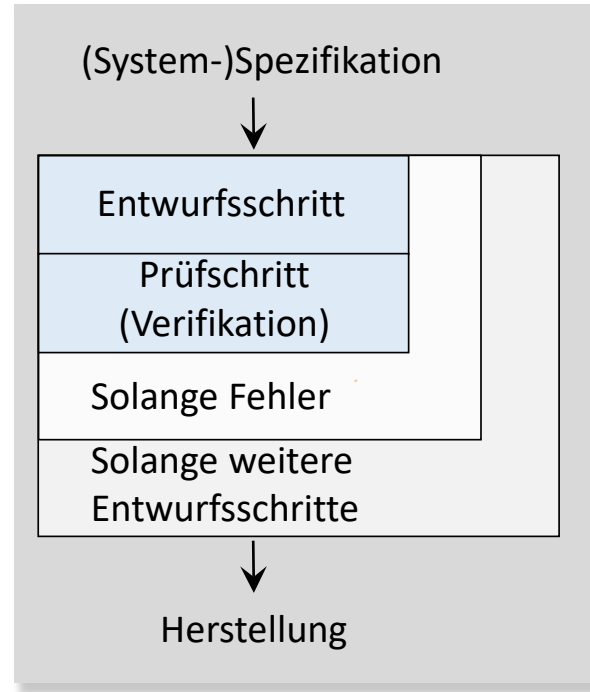
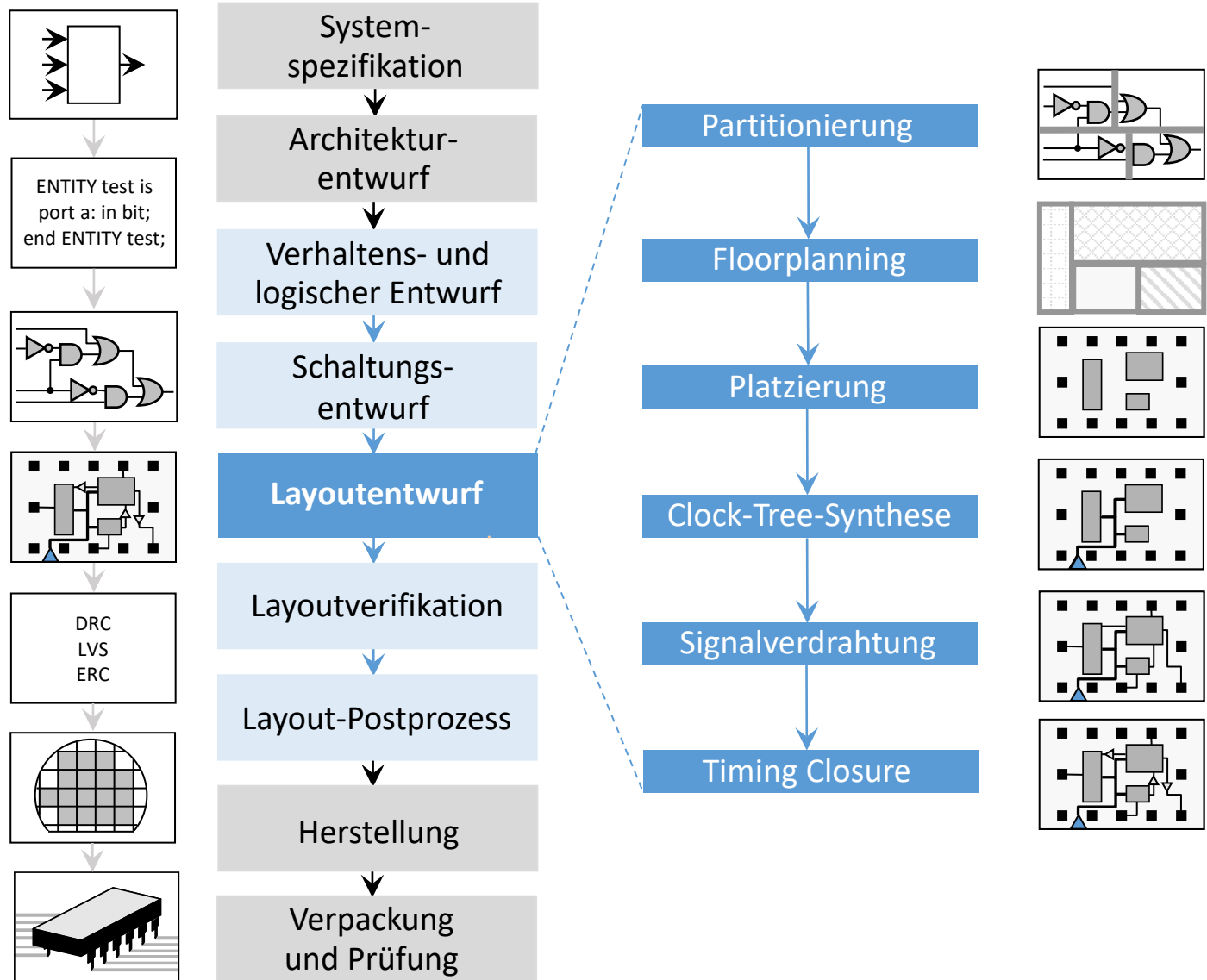


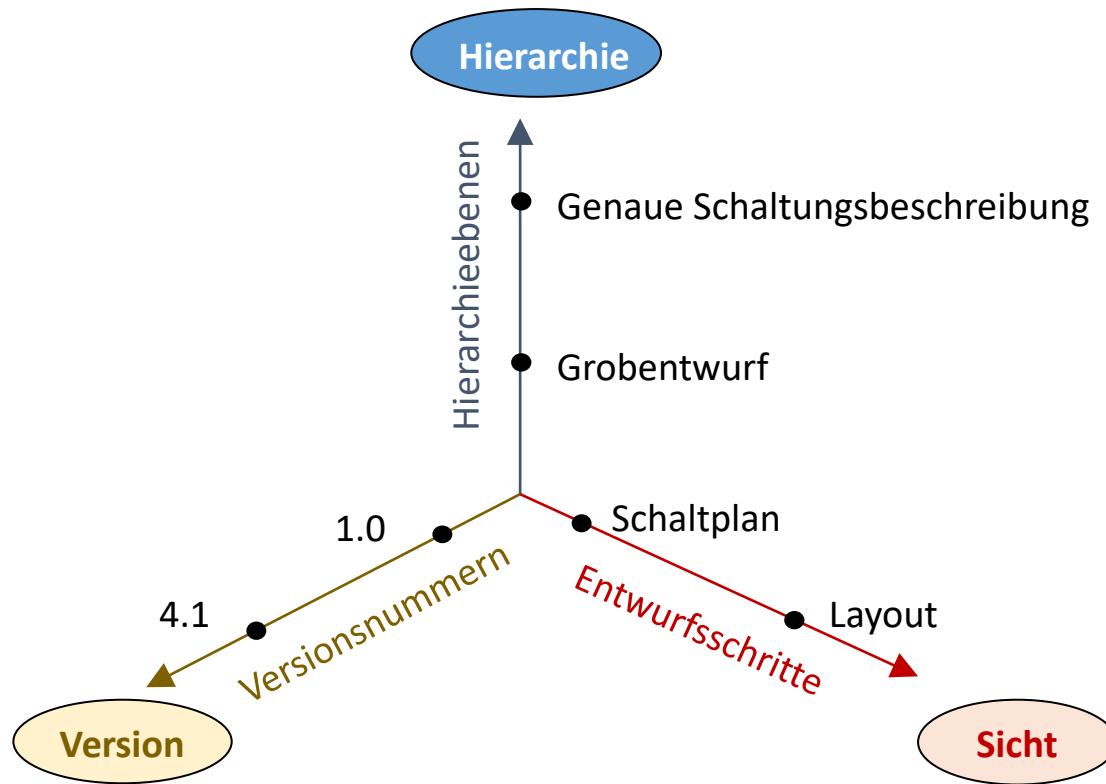
- 4.1 Entwurfsablauf
- 4.2 Entwurfsmodelle
- 4.3 Entwurfsstile
- 4.4 Entwurfsaufgaben und -werkzeuge
- 4.5 Optimierungsziele und Randbedingungen beim Layoutentwurf
- 4.6 Analoge und digitale Entwurfsabläufe
- 4.7 Visionen für die analoge Entwurfsautomatisierung

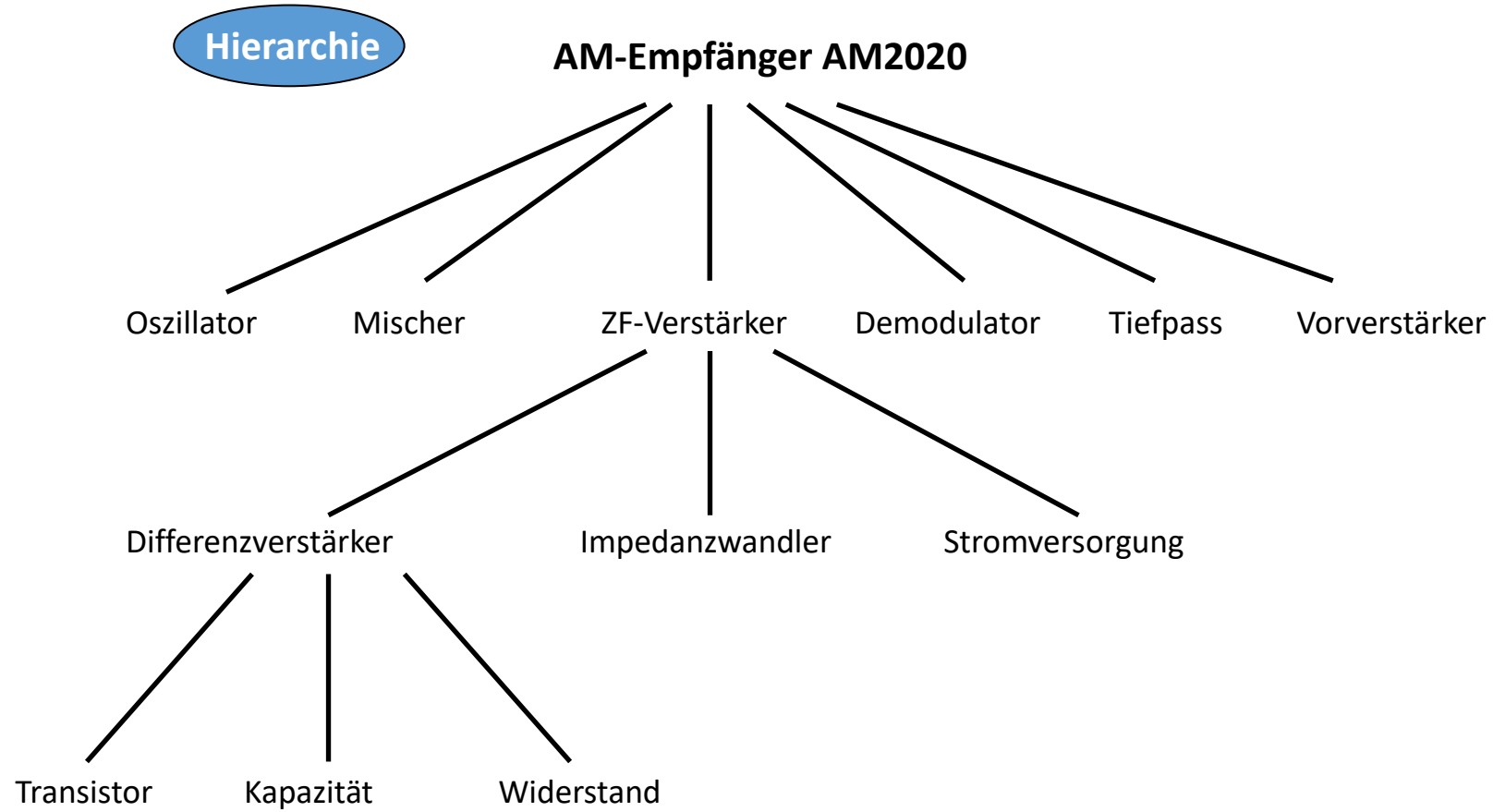


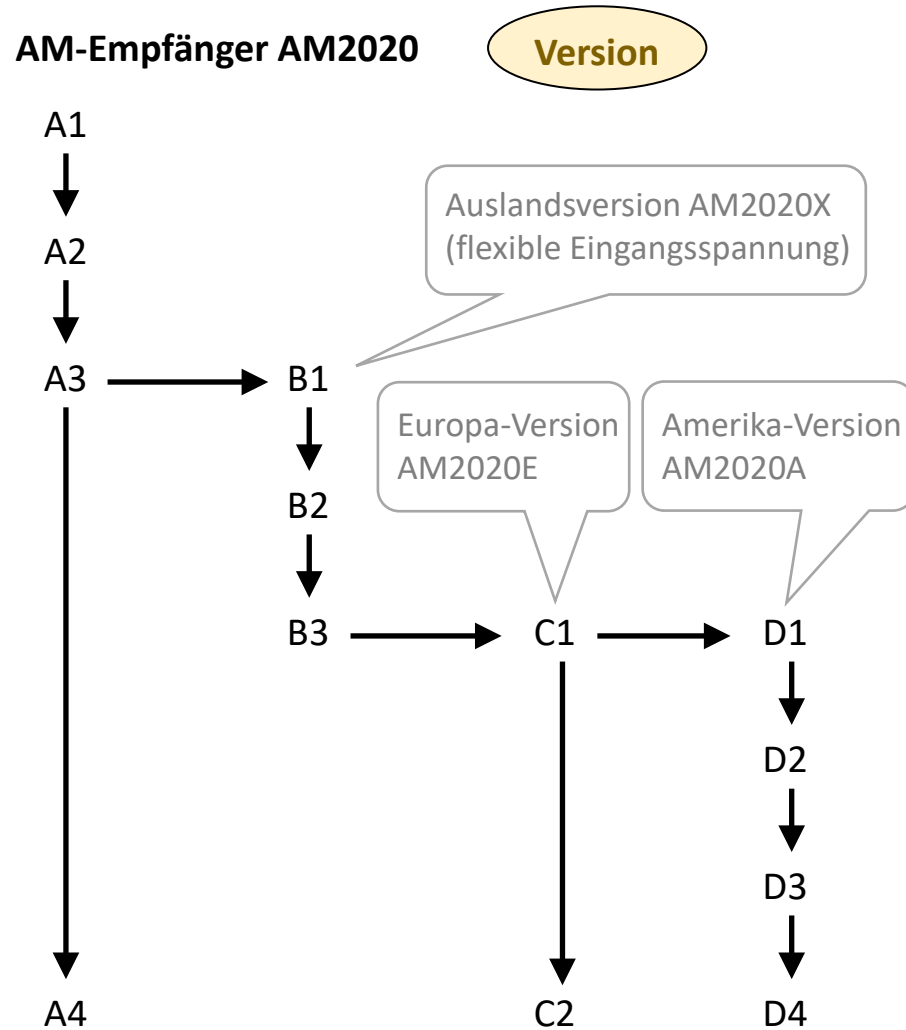


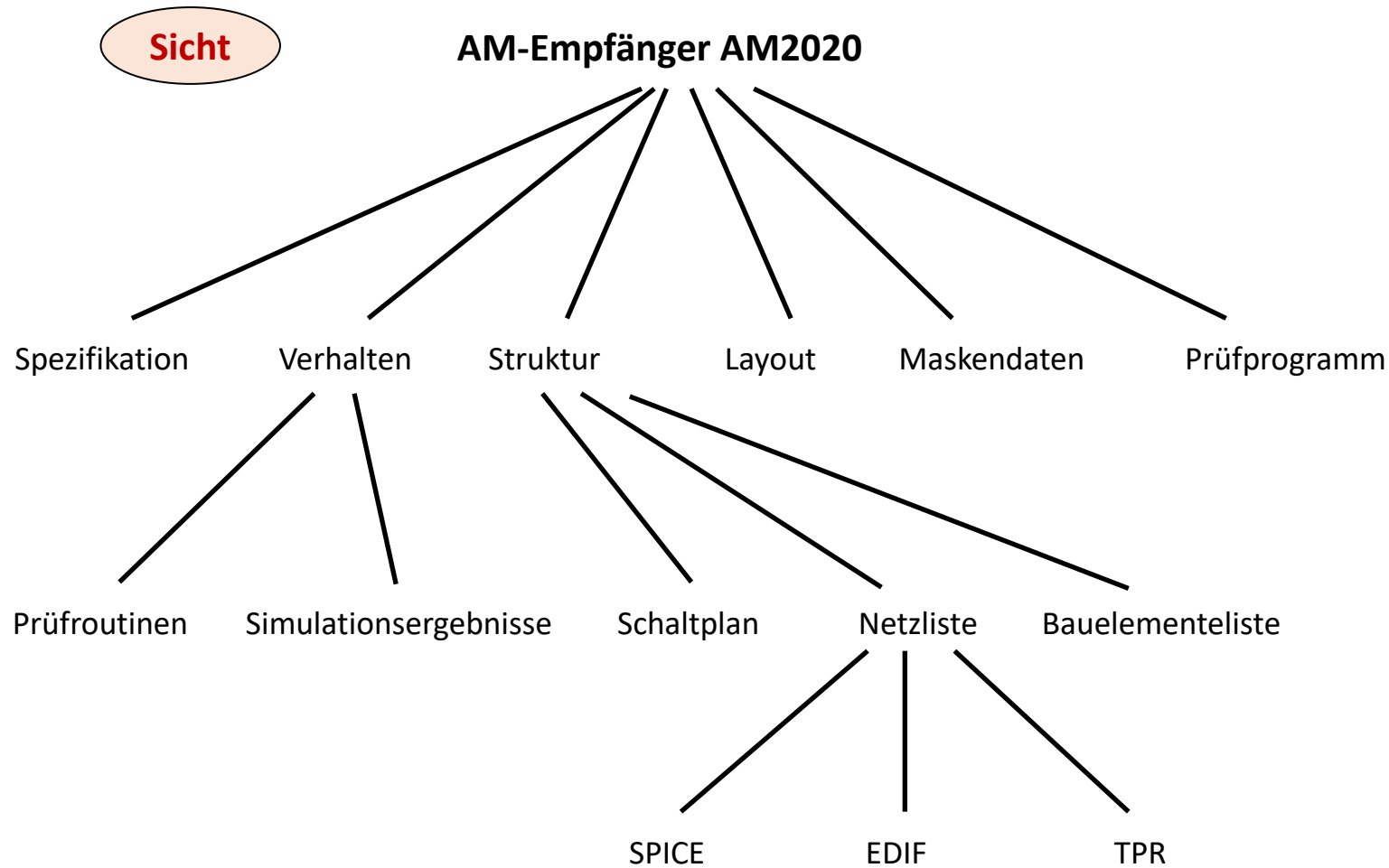


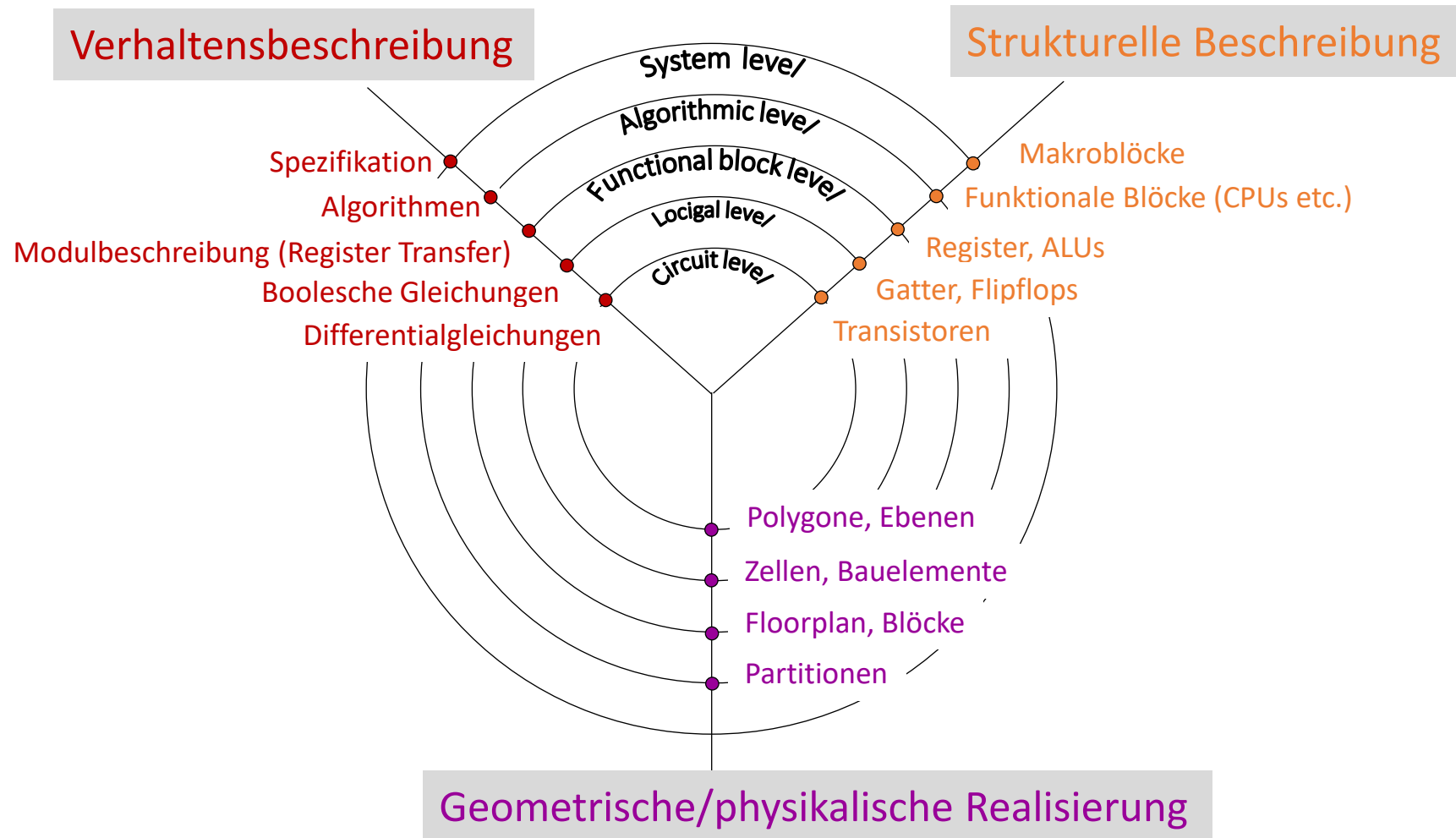








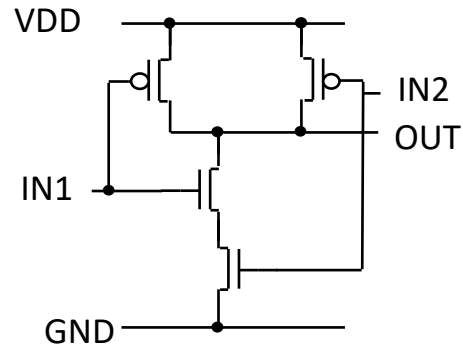




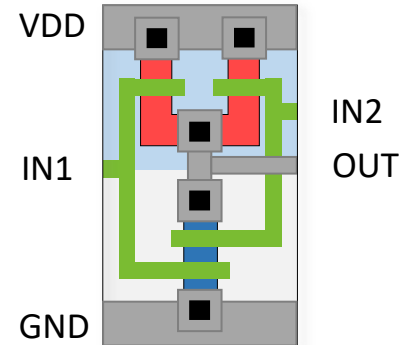
Verhaltens- beschreibung

IN1	IN2	OUT
0	0	1
0	1	1
1	0	1
1	1	0

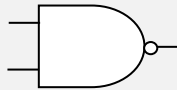
Strukturelle Beschreibung

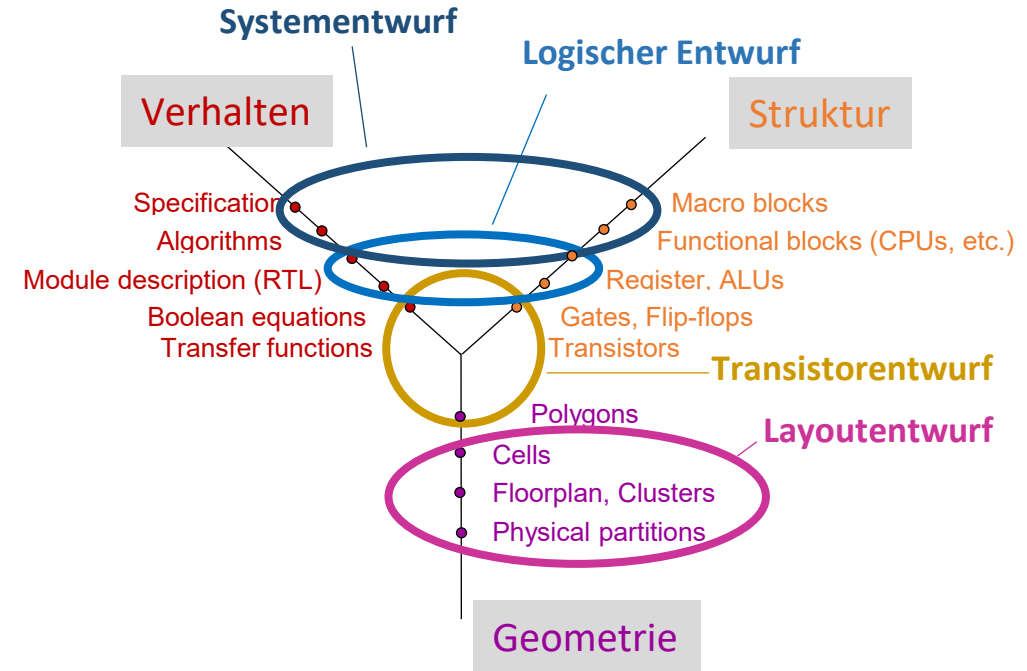
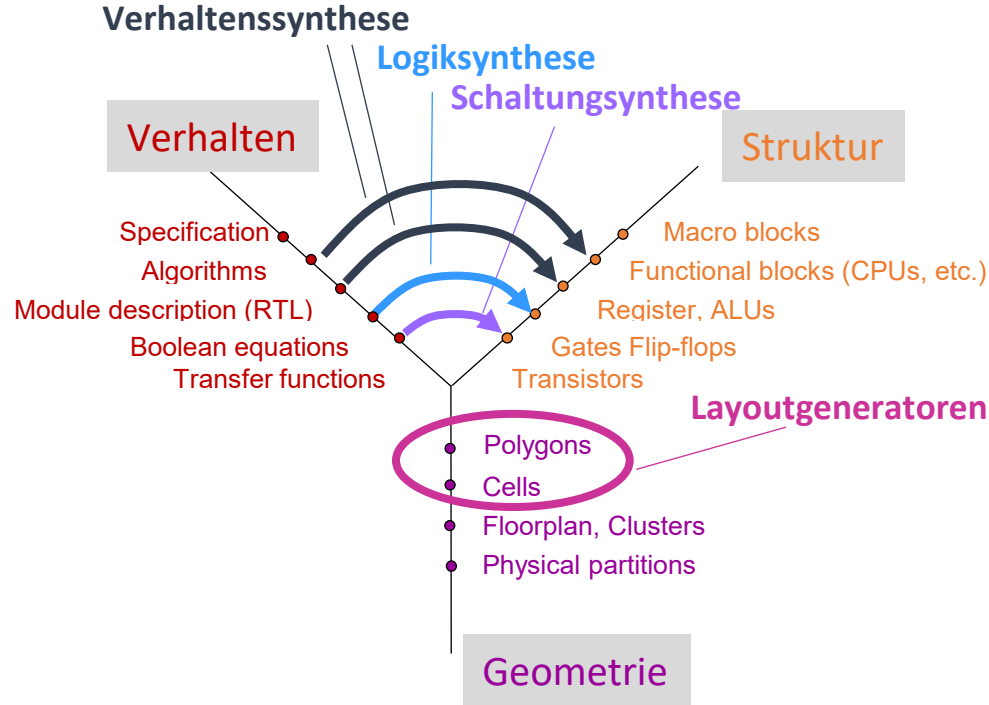


Geometrische/physikalische Realisierung

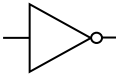


NAND gate



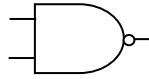


INV



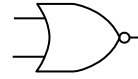
IN	OUT
0	1
1	0

NAND

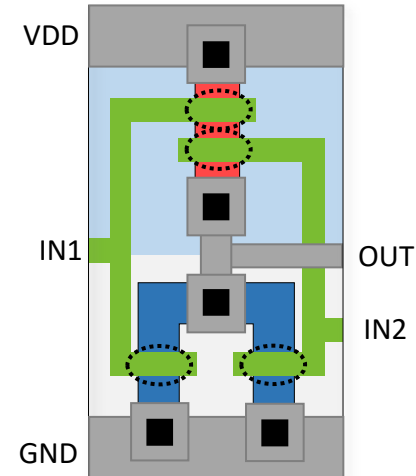
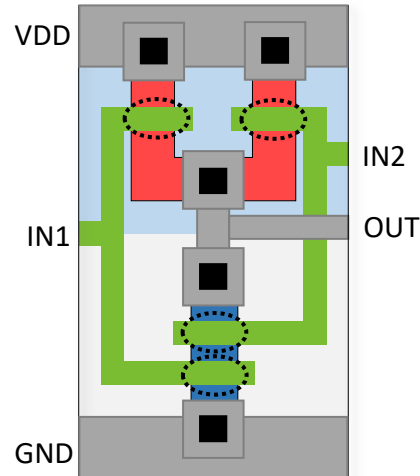
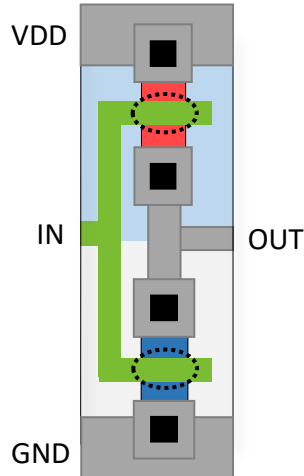


IN1	IN2	OUT
0	0	1
1	0	1
0	1	1
1	1	0

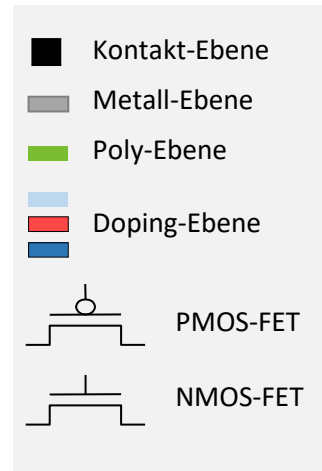
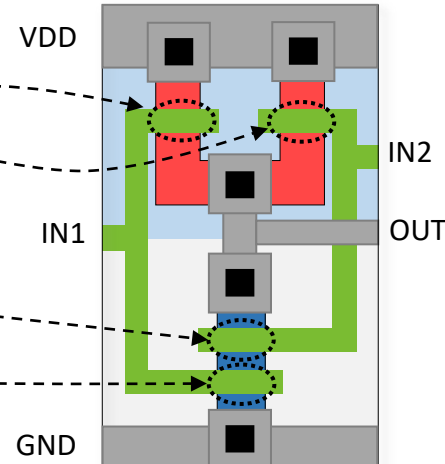
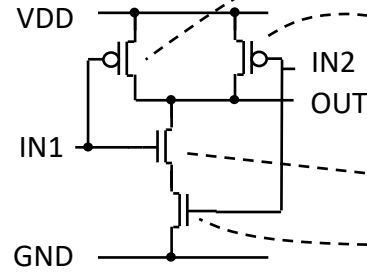
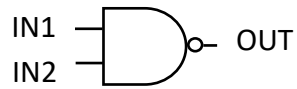
NOR



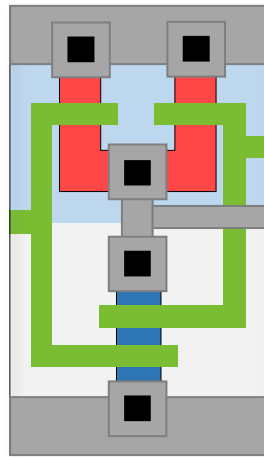
IN1	IN2	OUT
0	0	1
1	0	0
0	1	0
1	1	0



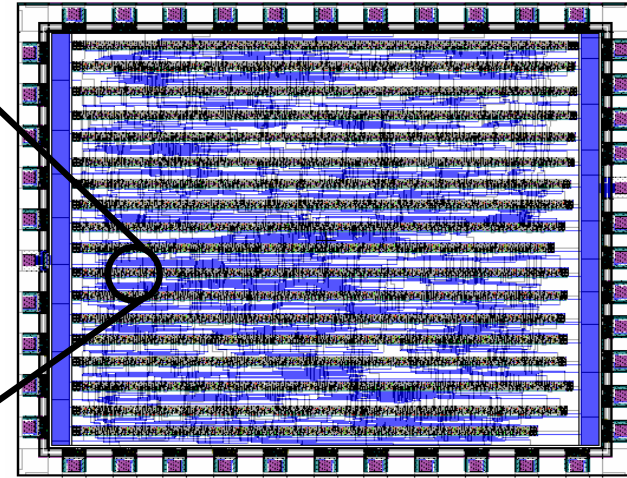
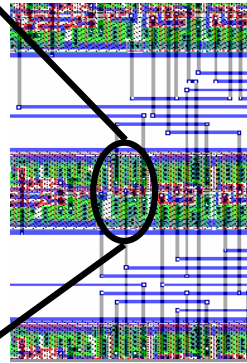
- Kontakt-Ebene
- Metall-Ebene
- Poly-Ebene
- n⁻-doping-Ebene
- p⁺-doping-Ebene
- n⁺-doping-Ebene
- Transistor

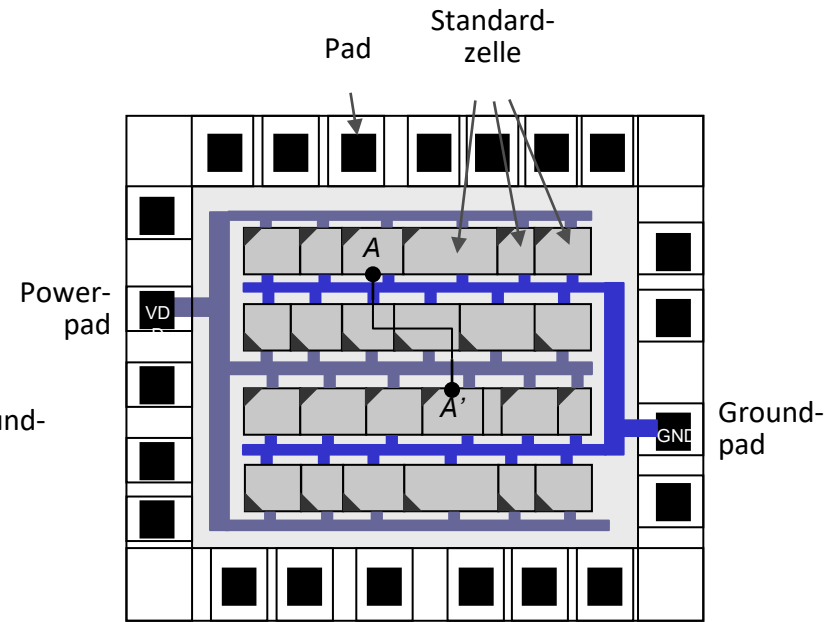
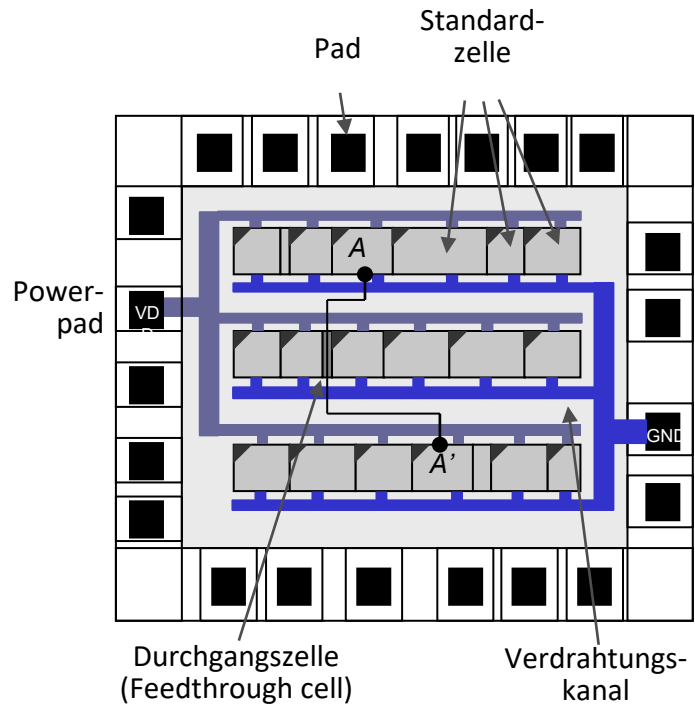


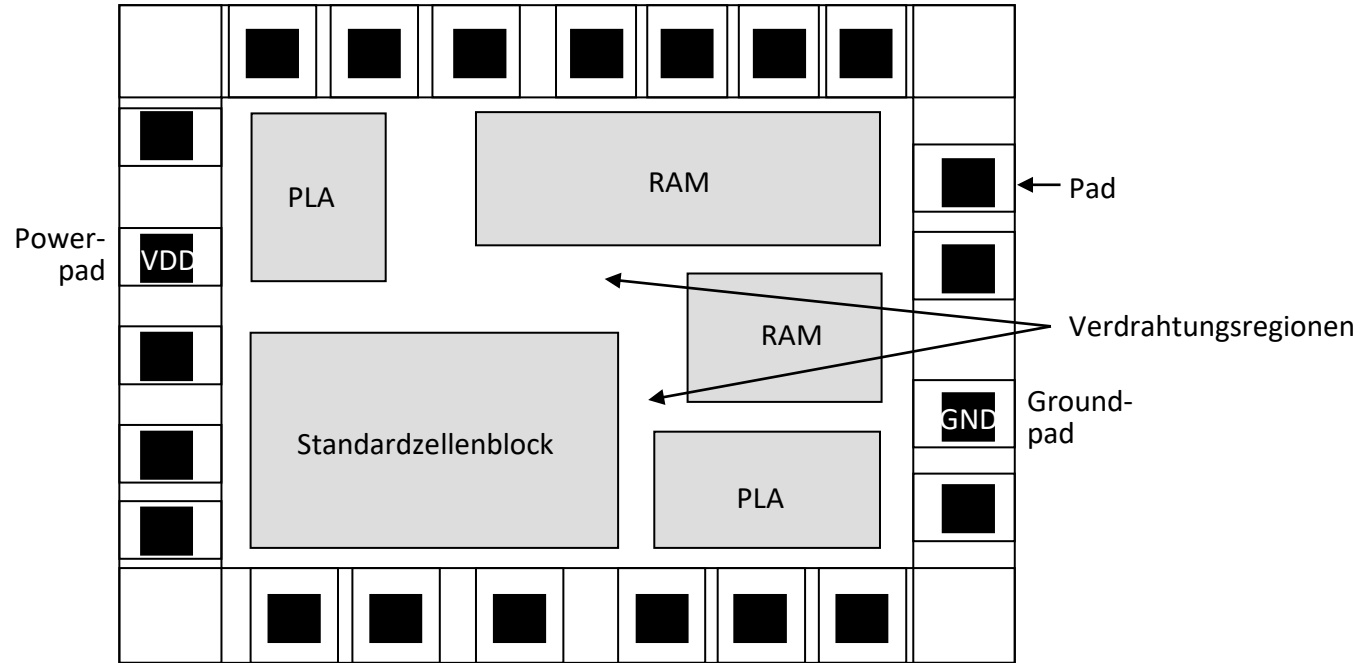
Power-(VDD)-Rail

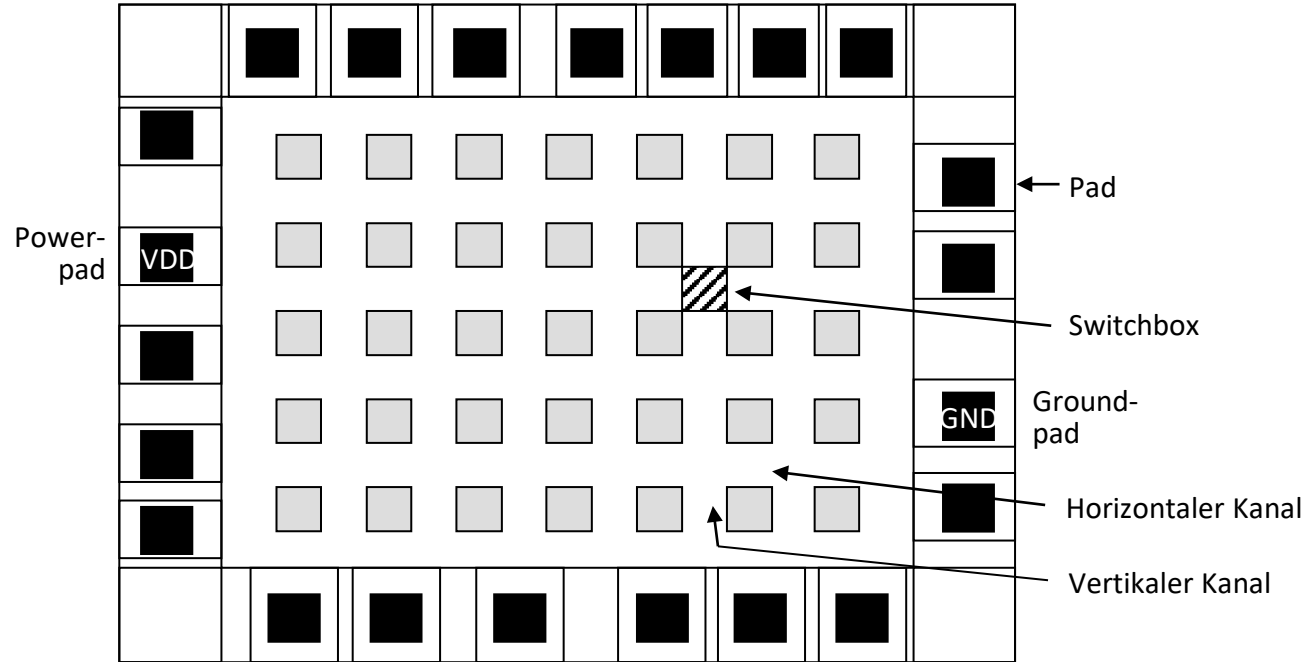


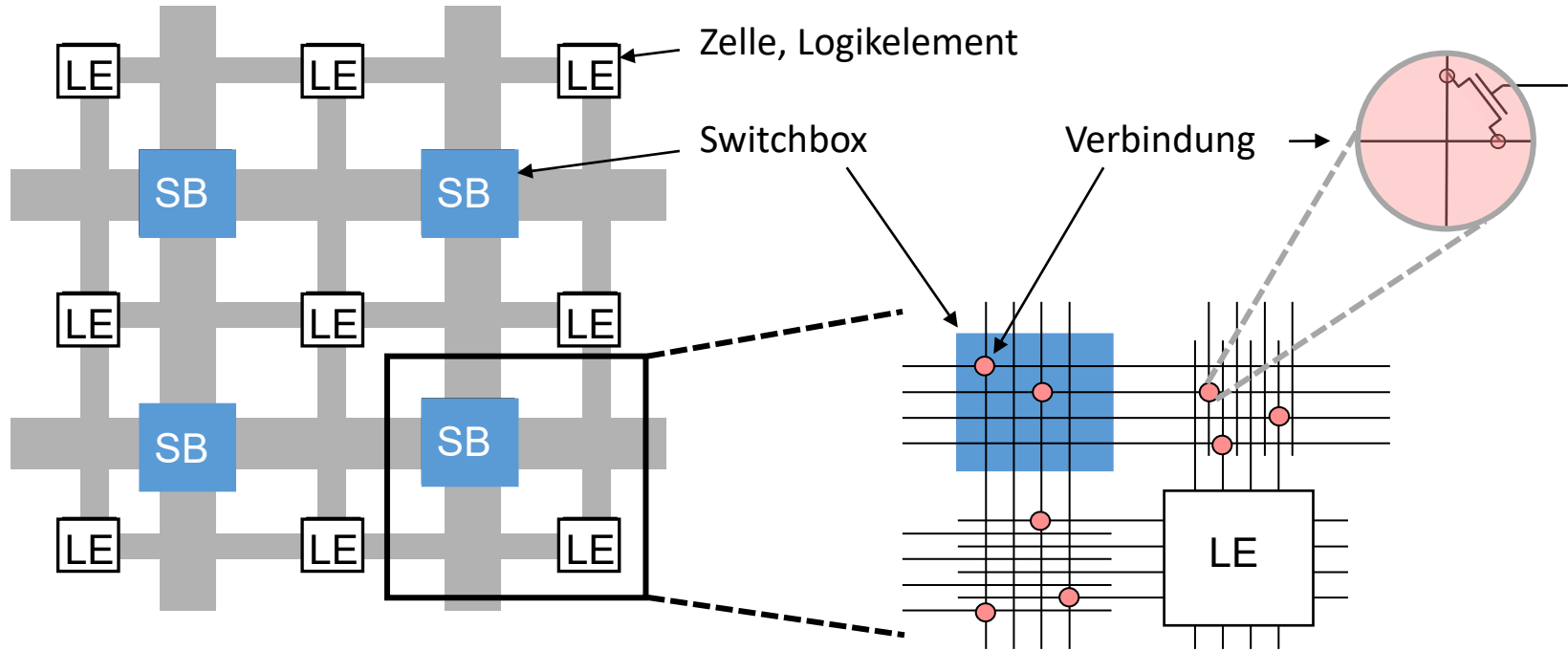
Ground-(GND)-Rail



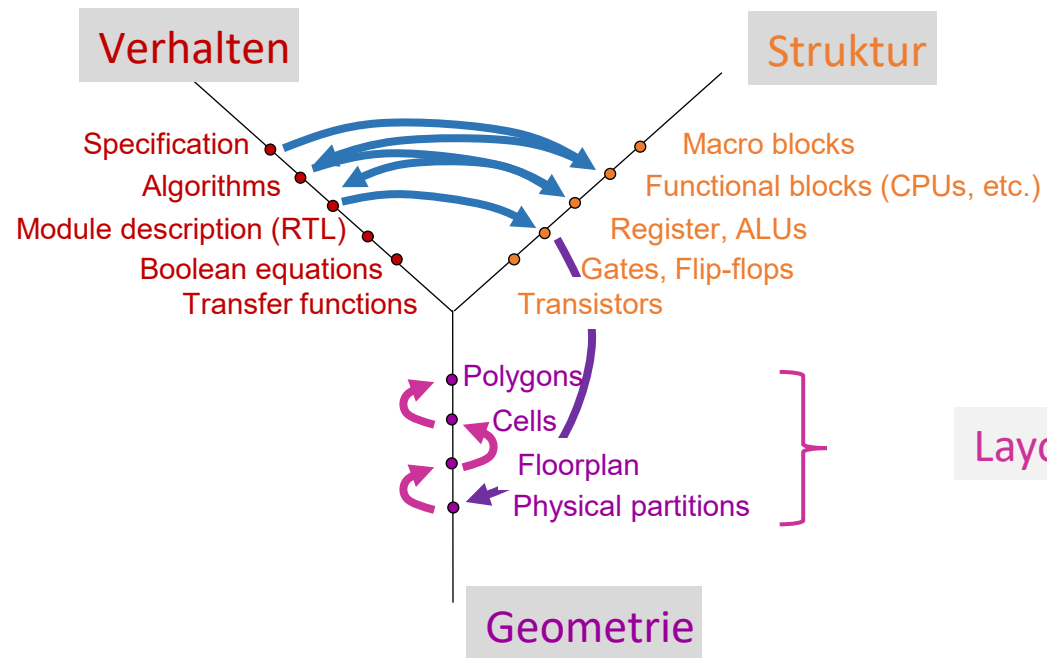




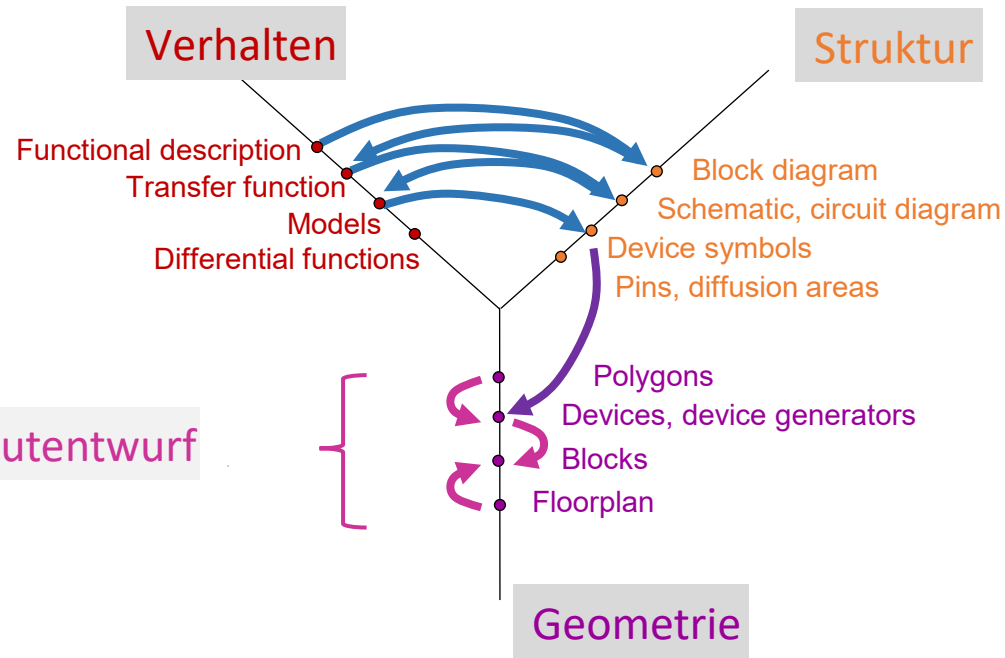


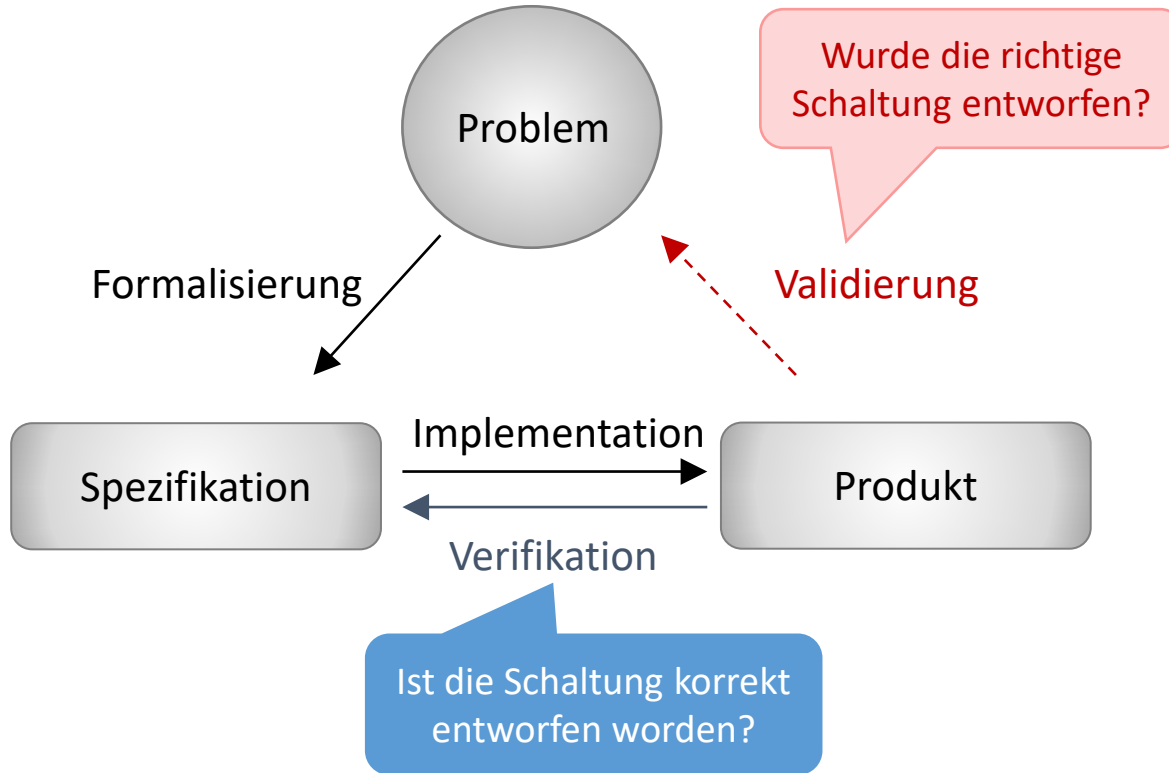


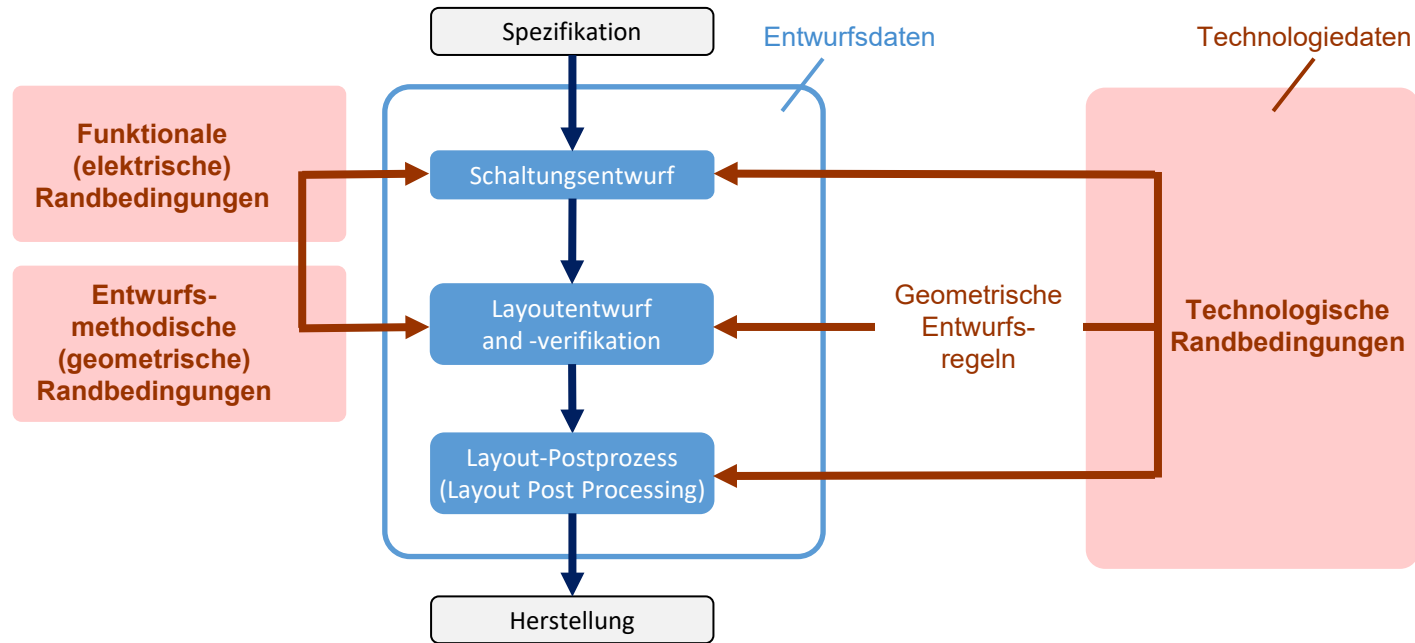
Entwurfstil	Entwurfskosten	Kosten der Maske	Fertigungskosten	Leistung	Wirtschaftliches Volumen
Kunden-spezifisch	Hoch	Hoch	Low	Hoch	Hoch
Standardzelle	Niedrig	Hoch	Mittel	Mittel	Mittlerer Bereich
Makrozelle	Hoch (Niedrig bei Wiederverwendung)	Hoch	Niedrig	Hoch	Mittlerer Bereich
Gate-Array	Niedrig	Mittel	Hoch	Niedrig	Niedrig
FPGA	Sehr niedrig	Keine	Hoch	Niedrig	Niedrig

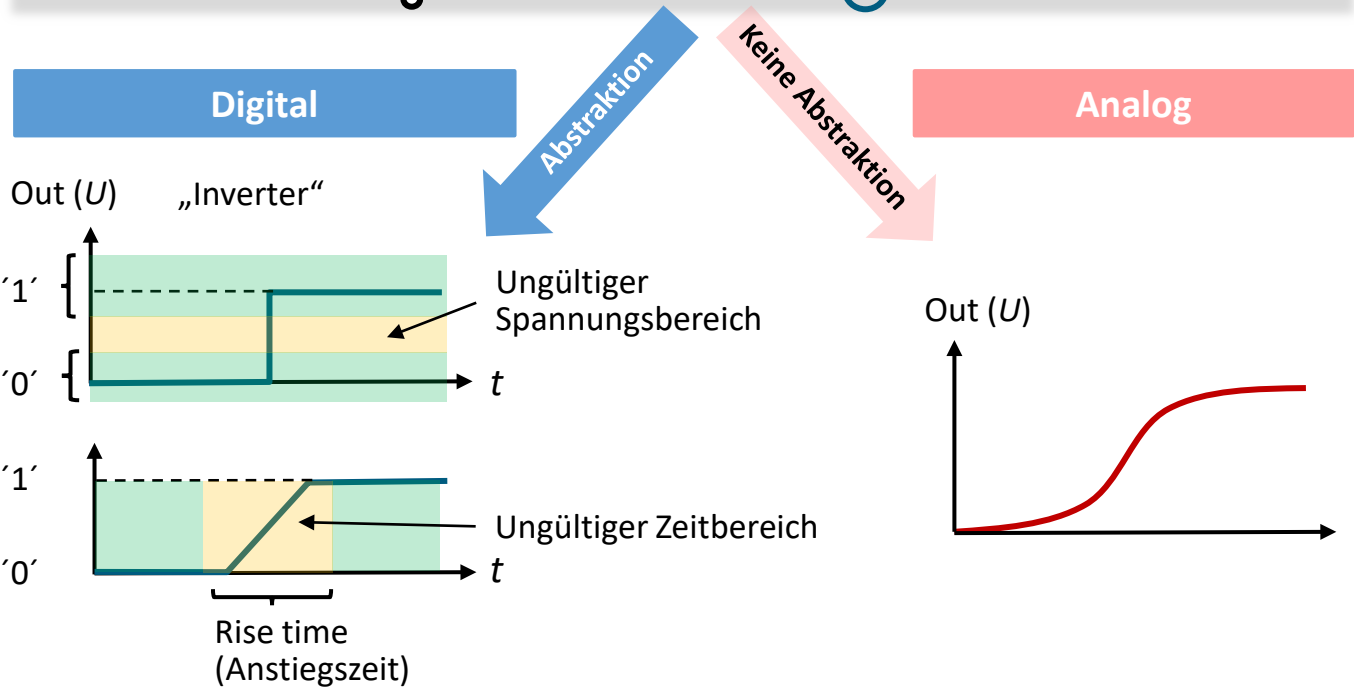
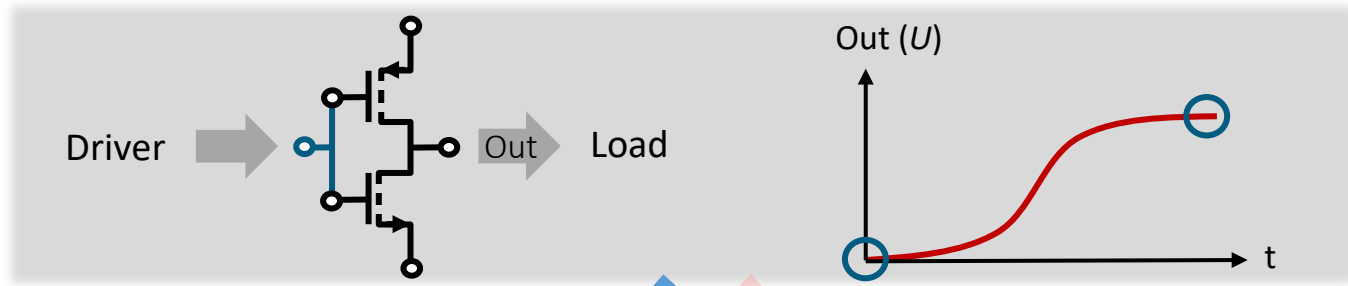


Layoutentwurf

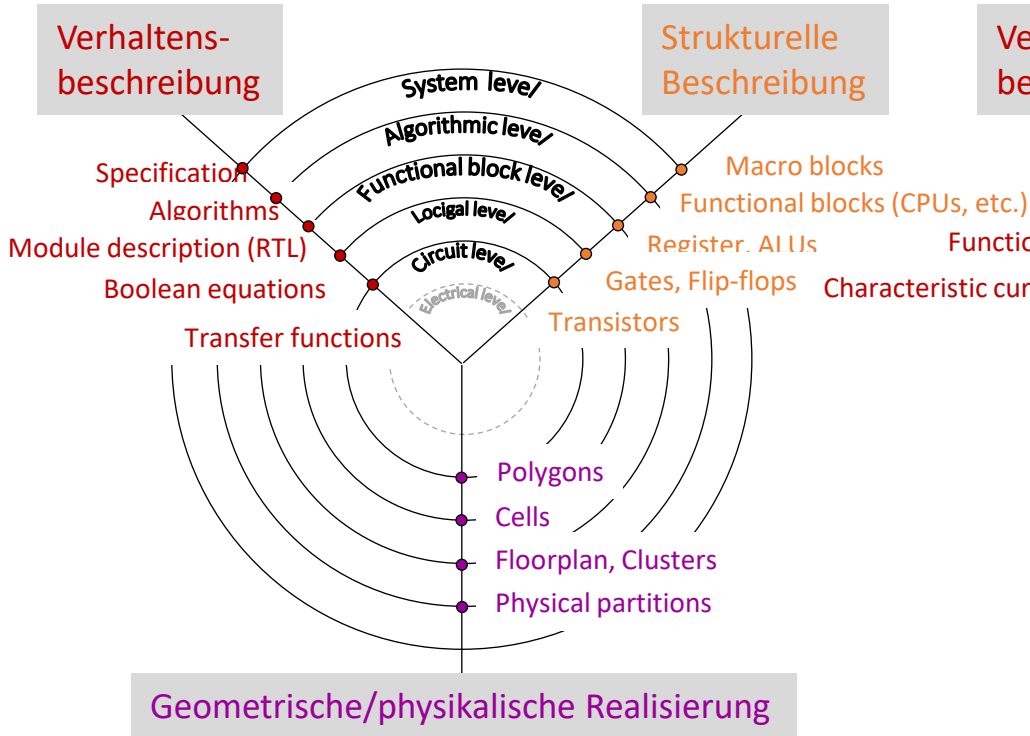




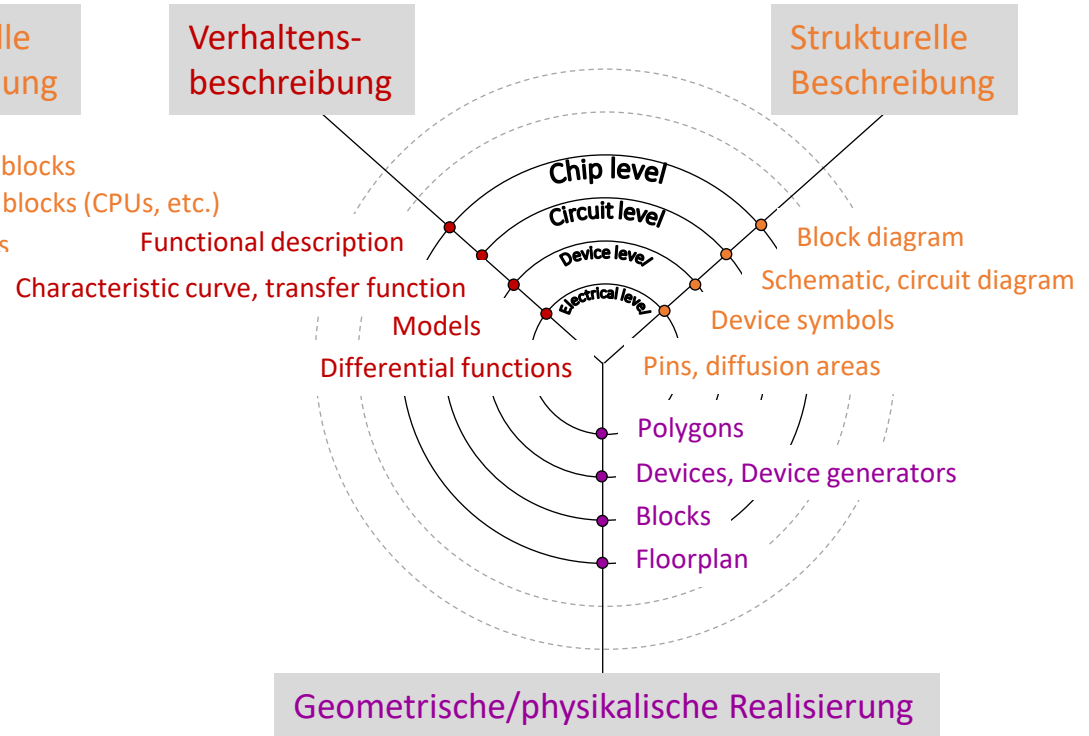


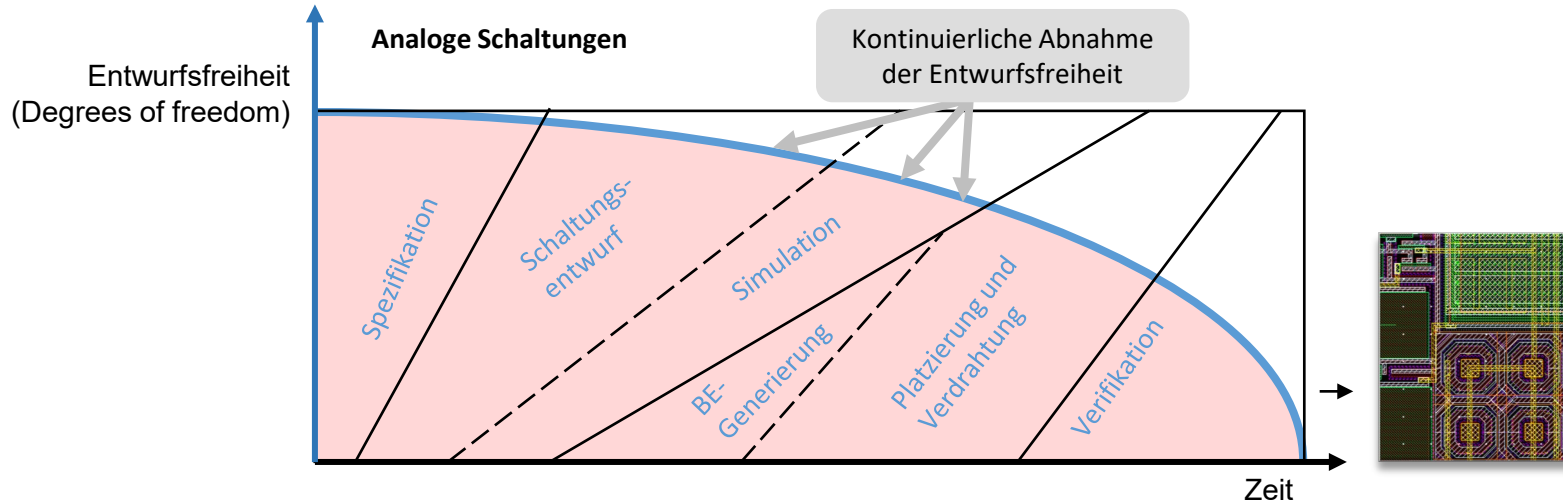
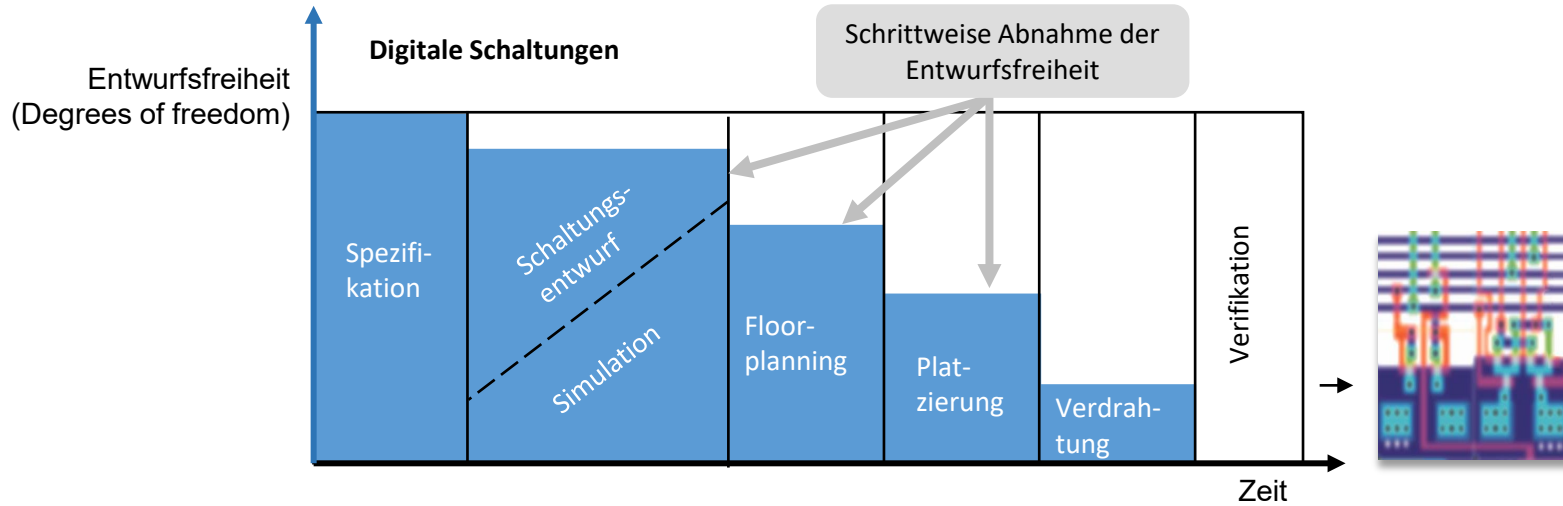


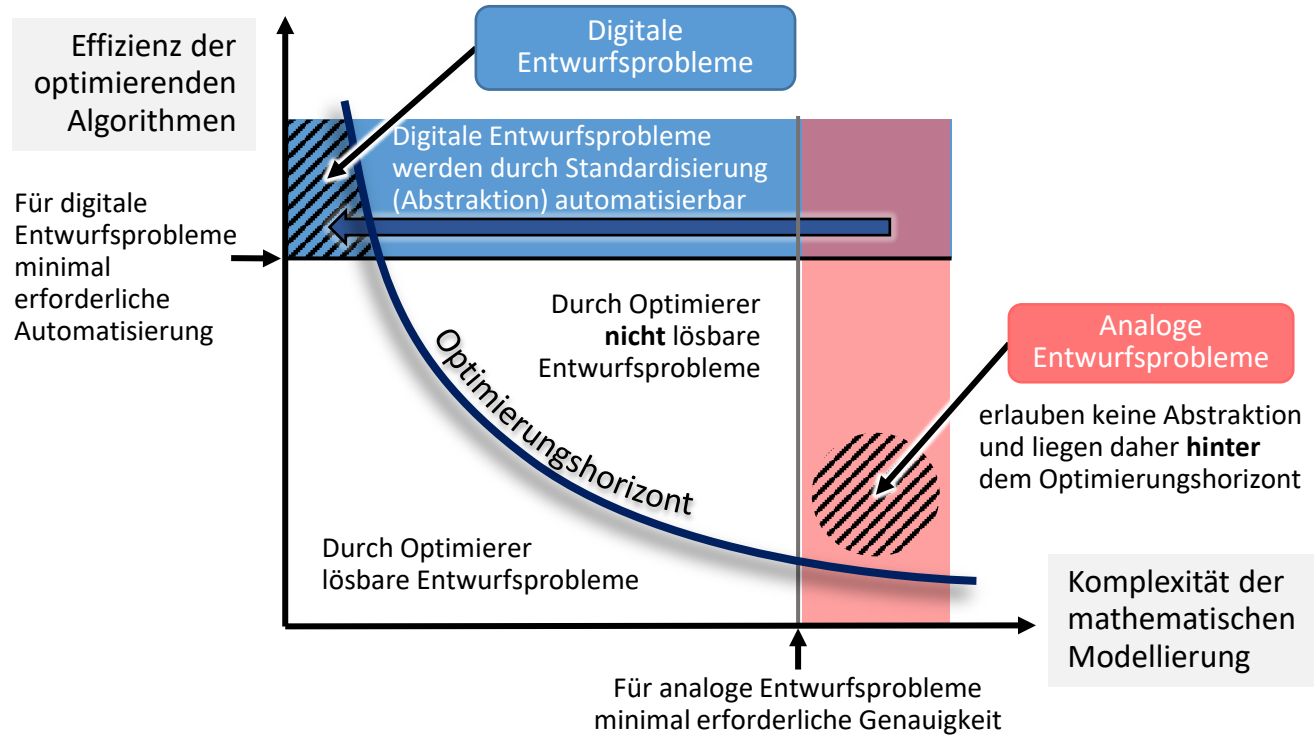
Digital



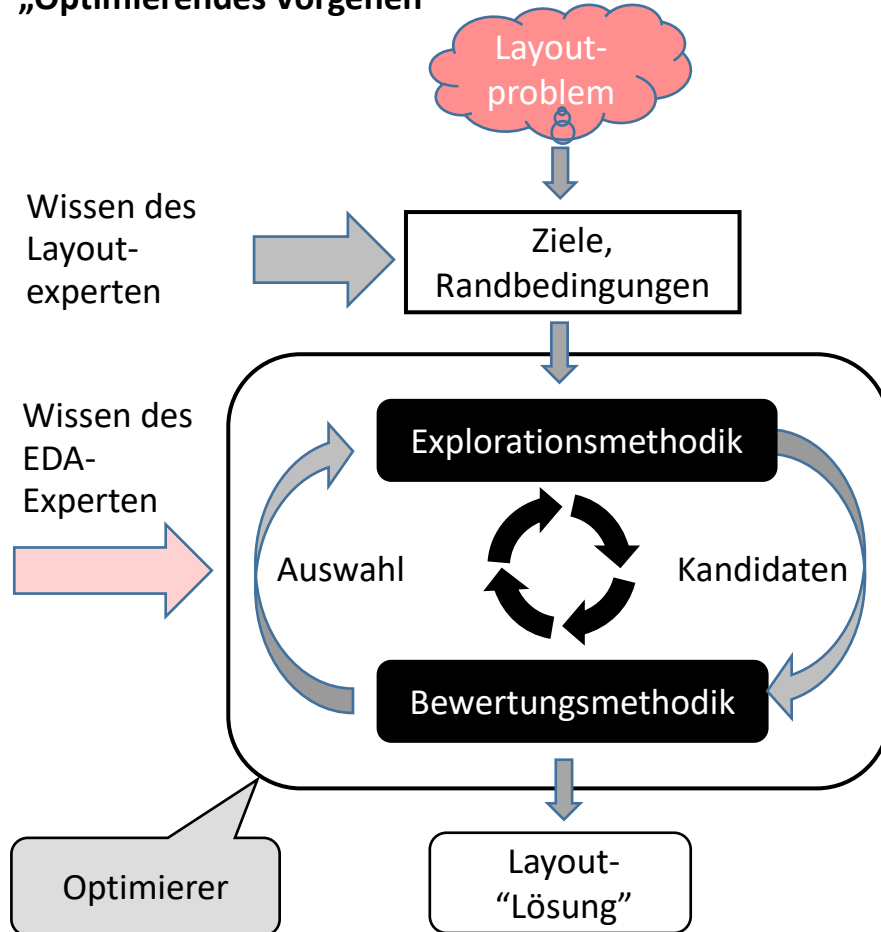
Analog



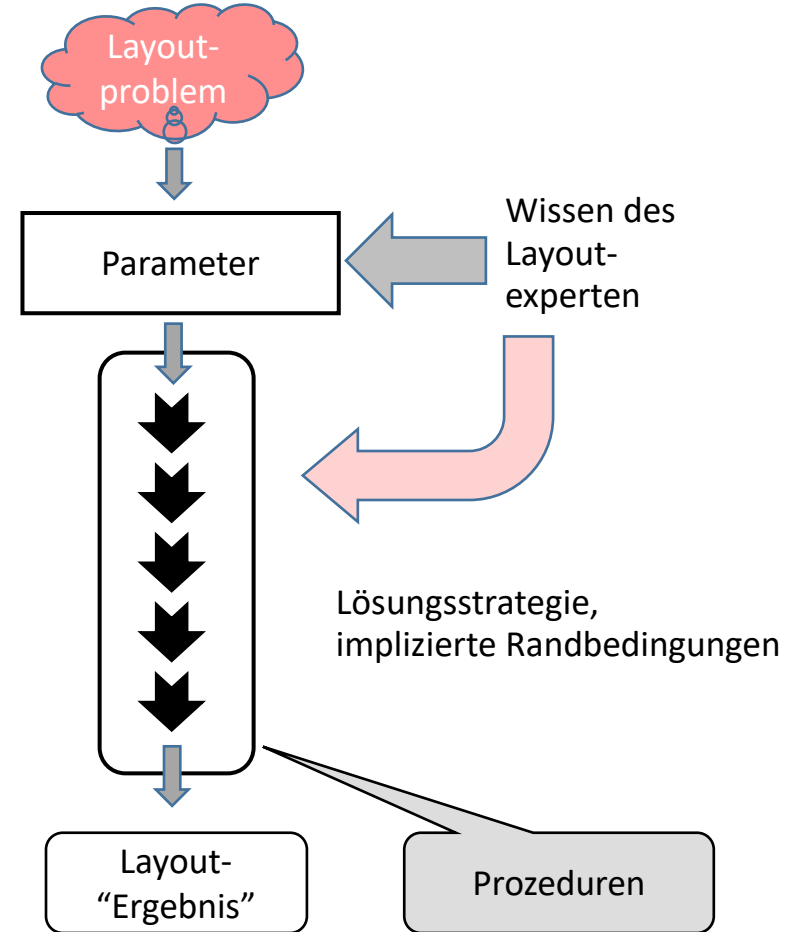




Top-down-Entwurfstil „Optimierendes Vorgehen“

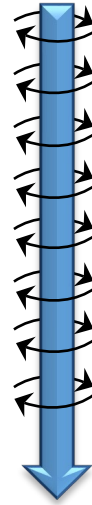


Bottom-up-Entwurfstil „Prozedurales Vorgehen“



Synthese-Schritte

Logiksynthese
Partitionierung
Floorplanning
Power-Verdrahtung
Globale Platzierung
Detaillierte Platzierung
Clock-Tree-Synthese
Globalverdrahtung
Feinverdrahtung
Timing Closure



Analyse- bzw. Verifikations-Schritte

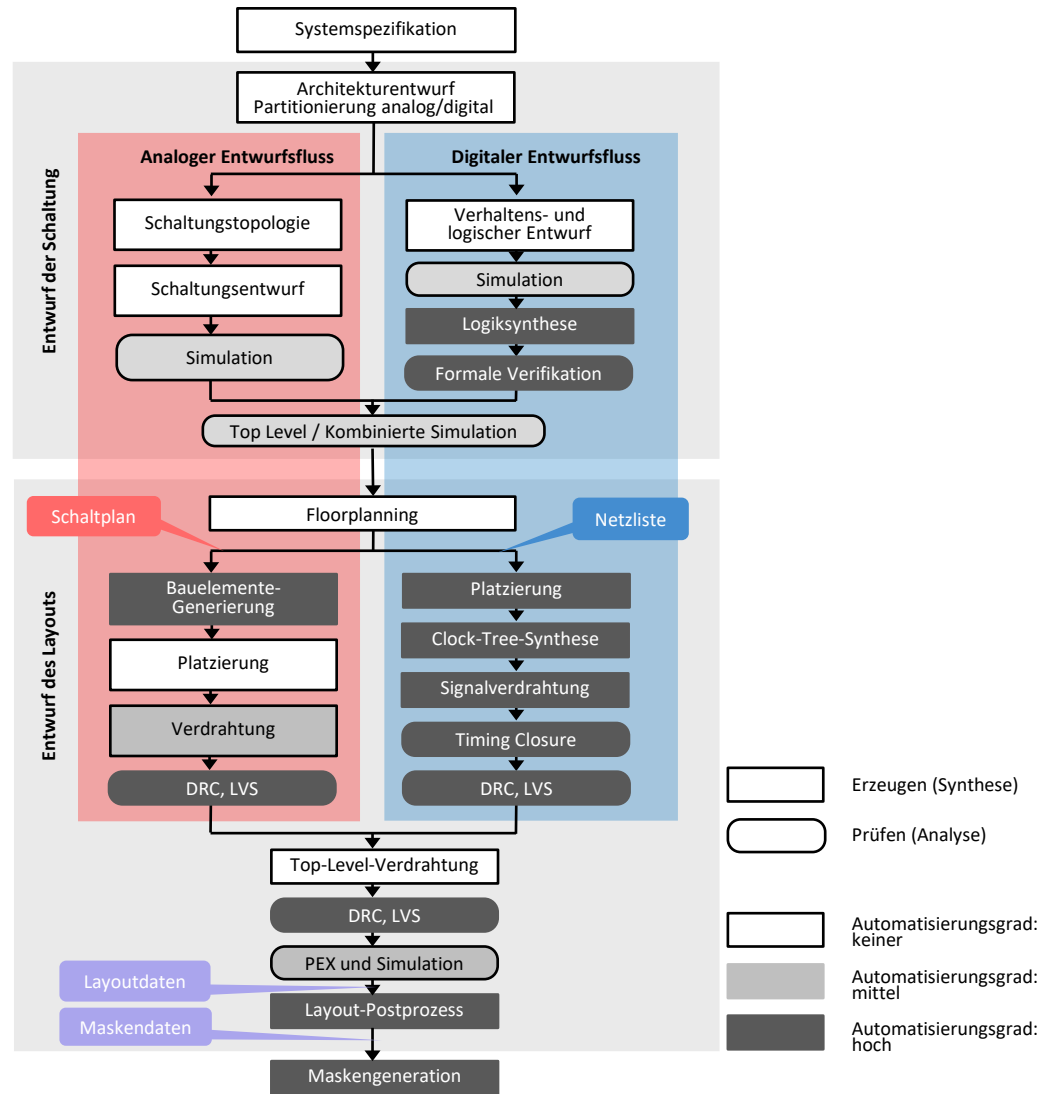
Formale Verifikation

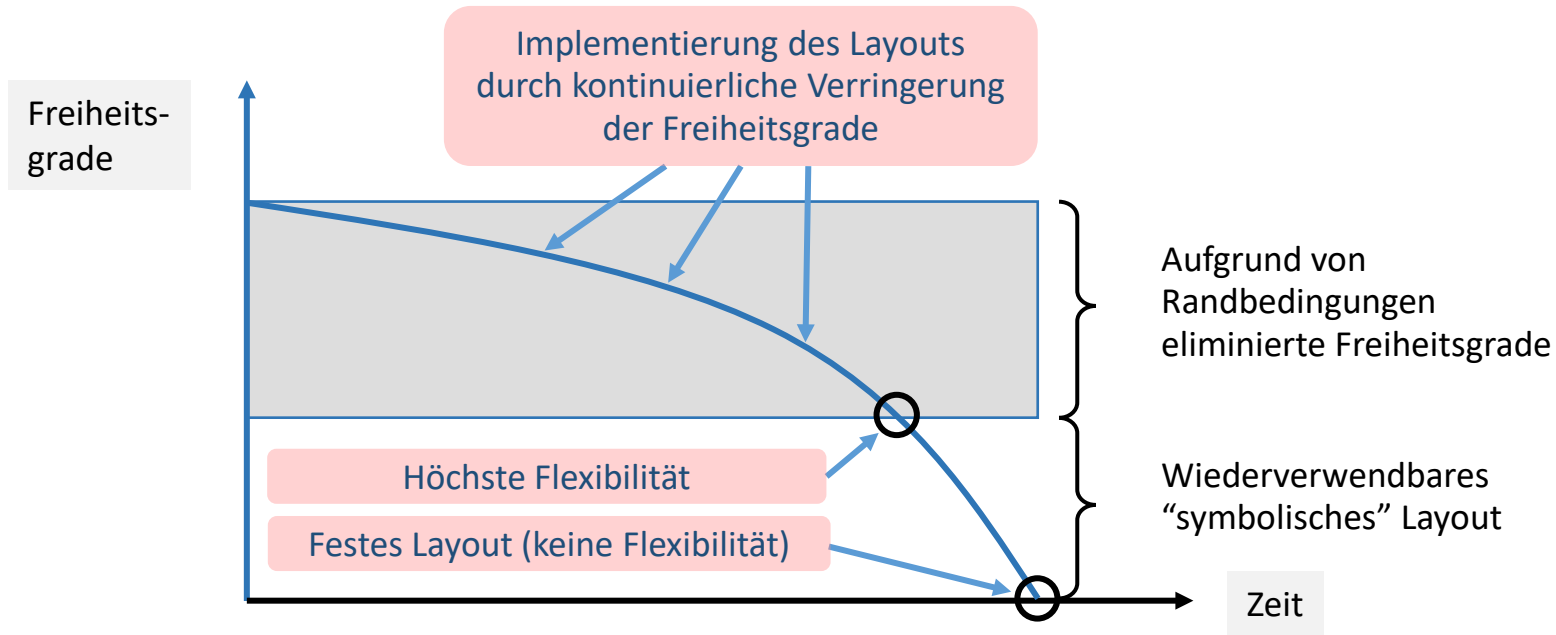
Globales Timing

Vorhersage der Verdrahtbarkeit

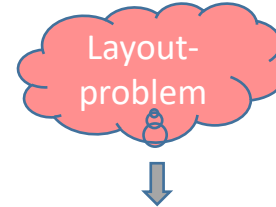
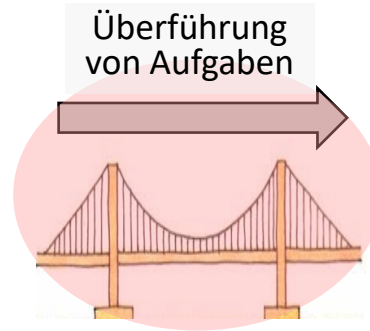
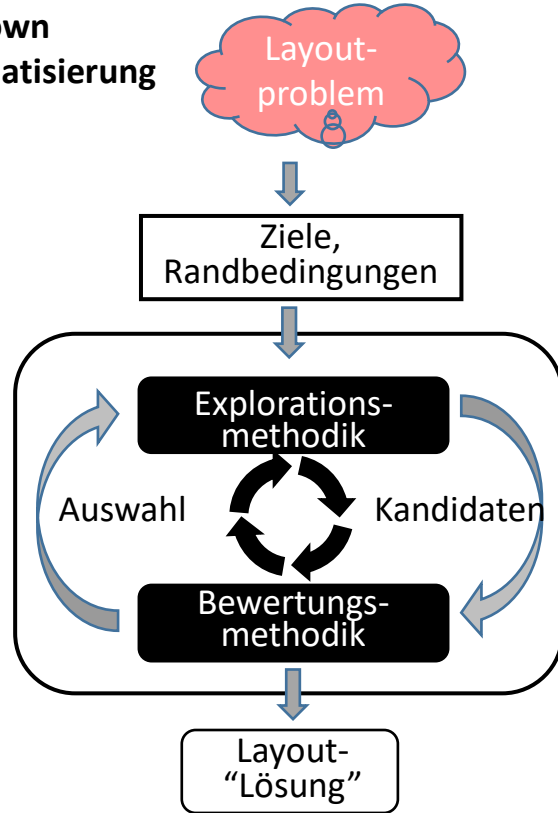
Timing

Parasitenextraktion
Sign-off DRC
Sign-off Timing
Sign-off Spice Simulation

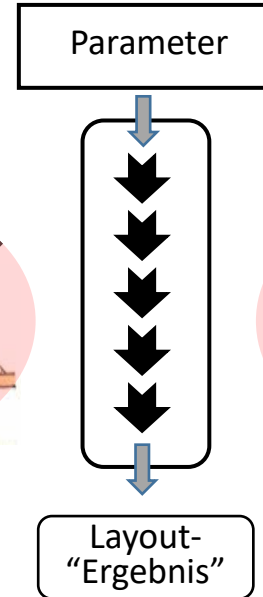




Top-down Automatisierung



Bottom-up Automatisierung



Expertenwissen,
Lösungsstrategien,
Implizierte Randbedingungen

